

MBR0520L SURFACE MOUNT SCHOTTKY BARRIER DIODE



Features

- Low Turn-on Voltage
- Fast Switching
- PN Junction Guard Ring Transient and ESD Protection
- Designed for Surface Mount Application
- Plastic Material —UL Recognition Flammability Classification 94V-0
- Green Products in Compliance with the ROHS Directive
- This is a Pb - Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Schematic & Pin Configuration



Mechanical Characteristics

- Case: SOD-123, Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Weight: 0.01 grams(approx)

Maximum Ratings@T_A=25°C unless otherwise specified

Characteristic	Symbol	MBR0520L	Units
Peak Repetitive Peak Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	20	V
RMS Reverse Voltage	V _{R(RMS)}	14	V
Average Rectified Output Current @T _L =75°C	I _O	0.5	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	5.5	A
Power Dissipation	P _d	410	mW
Typical Thermal Resistance Junction to Ambient	R _{θJA}	244	°C/W
Junction and Storage Temperature Range	T _{STG}	-65 to +150	°C

Electrical Characteristics@T_A=25°C unless otherwise specified

Characteristic	Symbol	Test Condition	Min	Typ	Max	Units
Forward Voltage*	V _F	@I _F =0.1A @I _F =0.5A	-	-	0.3 0.385	V
Reverse Leakage Current*	I _R	V _R =50% V _R =100% DC Blocking Voltage	-	-	75 250	μA
Diode capacitance	C _T	V _R =0V,f=1.0MHz	-	-	170	pF

* Pulse width < 300 μs, duty cycle < 2%

Ratings and Characteristics Curves

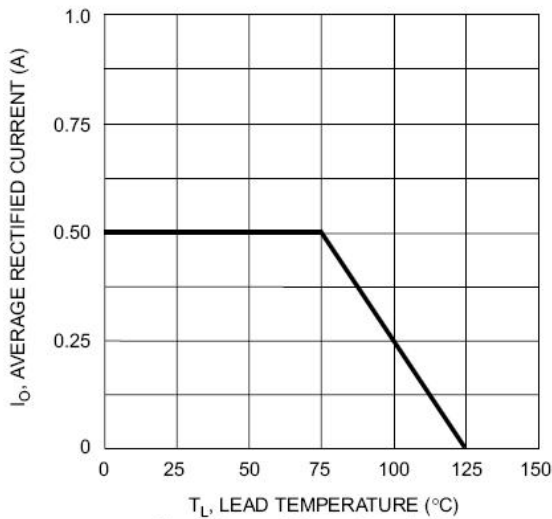


Fig. 1 Forward Current Derating Curve

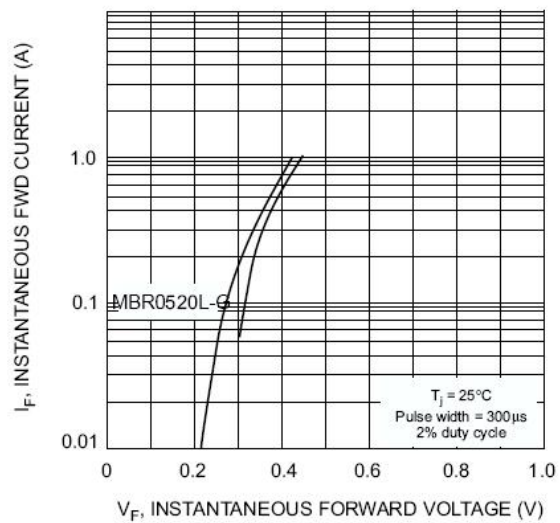


Fig. 2 Typical Forward Characteristics

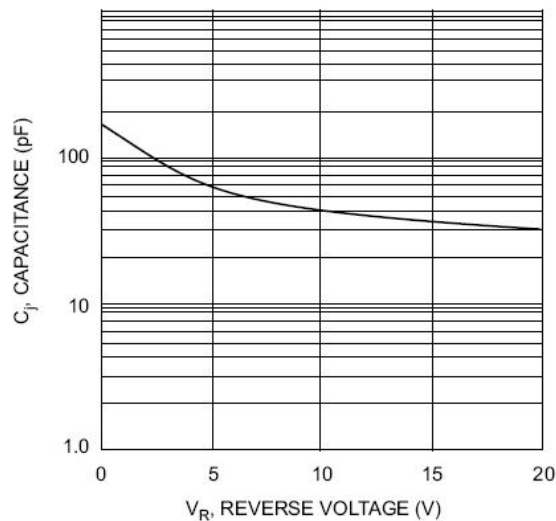


Fig. 3 Typ. Junction Capacitance vs Reverse Voltage

Ordering Information

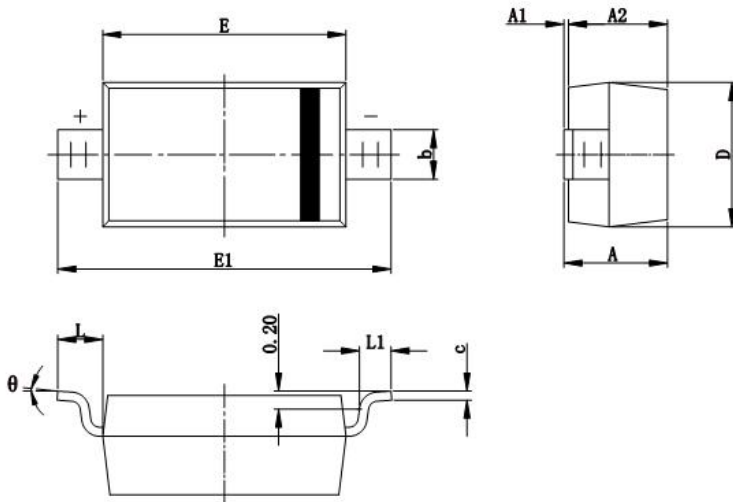
Device	Package	Shipping
MBR0520L	SOD-123 (Pb-Free)	3000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

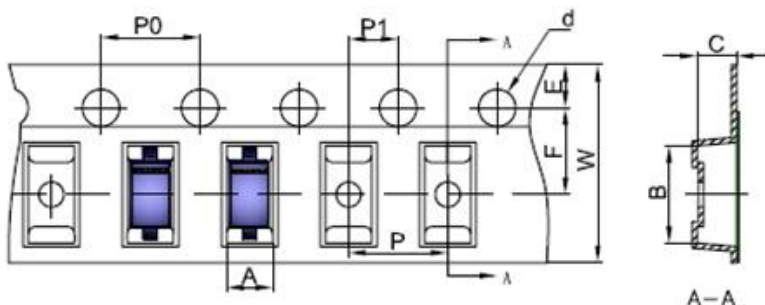
Marking Diagram


Where X is Date Code
 B2L = Marking code

Cautions: Molding resin
 Epoxy resin UL:94V-0

Mechanical Dimensions SOD-123


SYMBOL	Millimeters		Inches	
	MIN.	MAX.	MIN.	MAX.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.450	0.650	0.018	0.026
c	0.080	0.150	0.003	0.006
D	1.500	1.700	0.059	0.067
E	2.600	2.800	0.102	0.110
E1	3.550	3.850	0.140	0.152
L	0.500 REF.		0.020 REF.	
L1	0.250	0.450	0.010	0.018
θ	0°	8°	0°	8°

Carrier Tape Specification SOD-123


SYMBOL	Millimeters	
	Min.	Max.
A	1.80	1.90
B	3.89	3.99
C	1.52	1.62
d	1.45	1.65
E	1.65	1.85
F	3.40	3.60
P	3.90	4.10
P0	3.90	4.10
P1	1.90	2.10
W	7.90	8.30



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